COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: .VariantName

PCB VIEWED FROM BOTTOM SIDE

<table>
<thead>
<tr>
<th>BOARD #</th>
<th>TMDXICE110</th>
<th>REV: 1.1</th>
<th>SVN REV: Not In VersionControl</th>
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<td>TID #:</td>
<td>NA</td>
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<td>PLOT NAME = Multilayer Composite Print</td>
<td>GENERATED : 12/26/2016 8:48:53 PM</td>
<td>TEXAS INSTRUMENTS</td>
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